

规格书编号

SPEC NO :

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_  
PRODUCT 产品: \_\_\_\_\_ SAW FILTER \_\_\_\_\_  
MODEL NO 型号: \_\_\_\_\_ HDF736C SMD-4 \_\_\_\_\_  
MARKING 印字: \_\_\_\_\_ HDF4701 \_\_\_\_\_  
PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_  
APPROVED 批准: \_\_\_\_\_ D A T E 日期: \_\_\_\_\_ 2011-6-7 \_\_\_\_\_

|                         |             |         |
|-------------------------|-------------|---------|
| 客户确认 CUSTOMER RECEIVED: |             |         |
| 审核 CHECKED              | 批准 APPROVED | 日期 DATE |
|                         |             |         |

无锡市好达电子有限公司  
Shoulder Electronics Limited





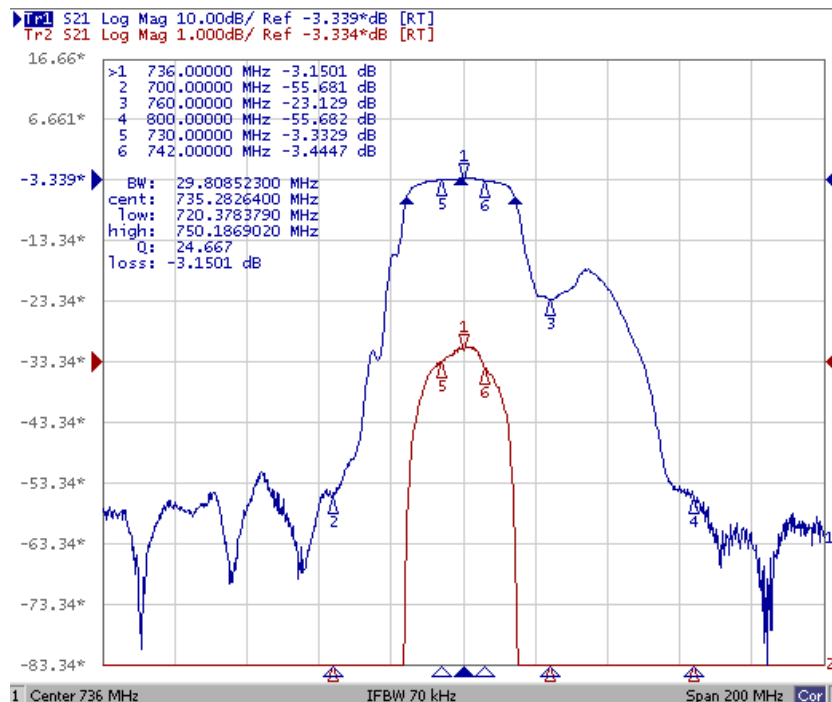
3.2 Maximum Rating

|                             |                |
|-----------------------------|----------------|
| Operation Temperature Range | -40°C to +85°C |
| Storage Temperature Range   | -45°C to +85°C |
| DC. Permissive Voltage      | 0 V DC. max.   |
| Maximum Input Power         | 5dBm           |

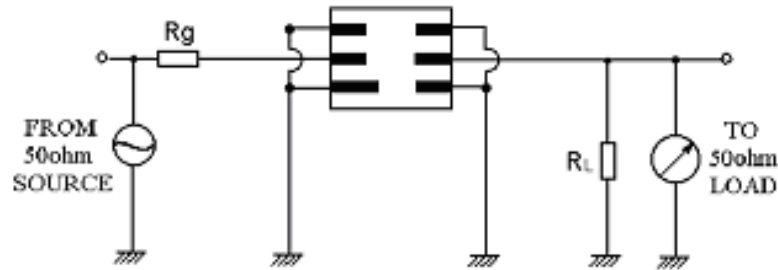
3.3 Electronic Characteristics

| Item                              | Specification      |
|-----------------------------------|--------------------|
| Center Frequency( $f_0$ )         | 736 MHz            |
| Insertion Loss(dB)                |                    |
| 1.)736.0MHz                       | 4.5 dB max         |
| 2.)600-700 MHz                    | 45 dB min          |
| 3.)760-800 MHz                    | 20 dB min          |
| 4.)800-900 MHz                    | 45 dB min          |
| Passband width(-3dB)              | $\pm 11.0$ MHz min |
| Ripple deviation (730-742MHz)(dB) | 2.0 max            |
| Input/output Impedance(Nominal)   | 50 $\Omega$        |

3.4 Frequency Characteristics



### 3.5 Test Circuit



## 4. ENVIRONMENTAL CHARACTERISTICS

### 4-1 Temperature cycling

Subject the device to a low temperature of  $-40^{\circ}\text{C}$  for 30 minutes. Following by a high temperature of  $+25^{\circ}\text{C}$  for 5 Minutes and a higher temperature of  $+85^{\circ}\text{C}$  for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 3.3.

### 4-2 Resistance to solder heat

Submerge the device terminals into the solder bath at  $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for  $10 \pm 1$  sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 3.3.

### 4-3 Solderability

Submerge the device terminals into the solder bath at  $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 3.3.

### 4-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in 3.3.

### 4-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 3.3.

## 5. REMARK

### 5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please

avoid ultrasonic cleaning

### 5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

## 6. Packing

### 6.1 Dimensions

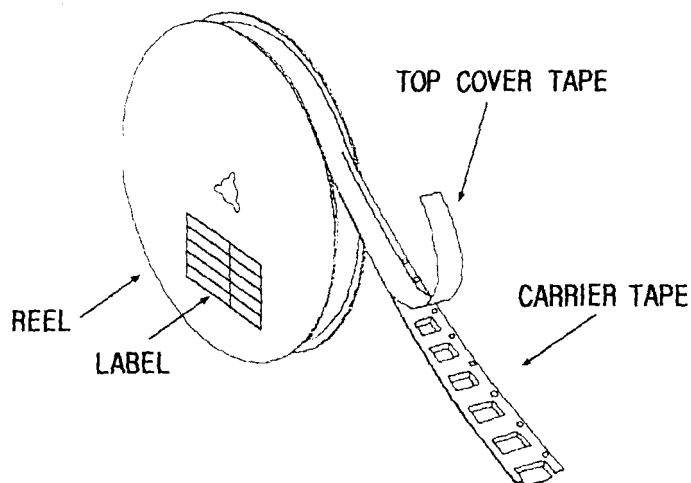
- (1) Carrier Tape: Figure 1
- (2) Reel: Figure 2
- (3) The product shall be packed properly not to be damaged during transportation and storage.

### 6.2 Reeling Quantity

- 1000 pcs/reel 7''  
3000 pcs/reel 13''

### 6.3 Taping Structure

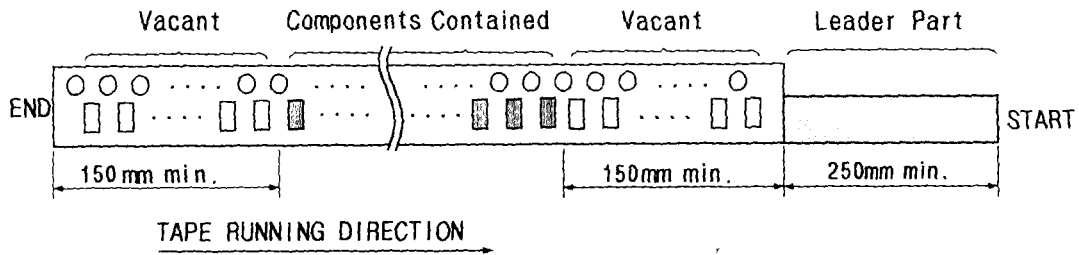
- (1) The tape shall be wound around the reel in the direction shown below.



- (2) Label

|                   |  |
|-------------------|--|
| Device Name       |  |
| User Product Name |  |
| Quantity          |  |
| Lot No.           |  |

- (3) Leader part and vacant position specifications.

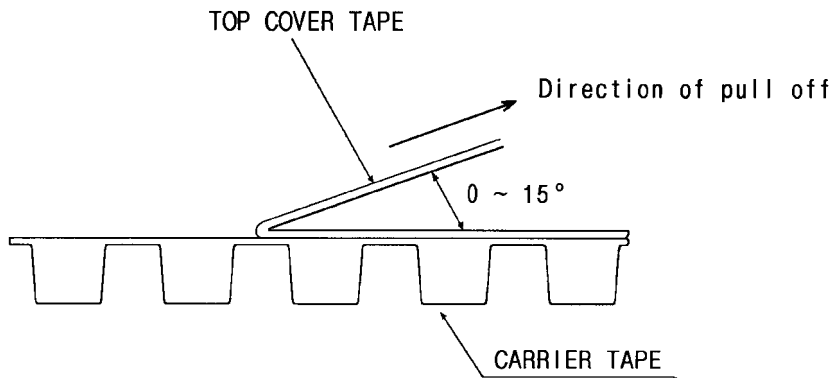


## 7. TAPE SPECIFICATIONS

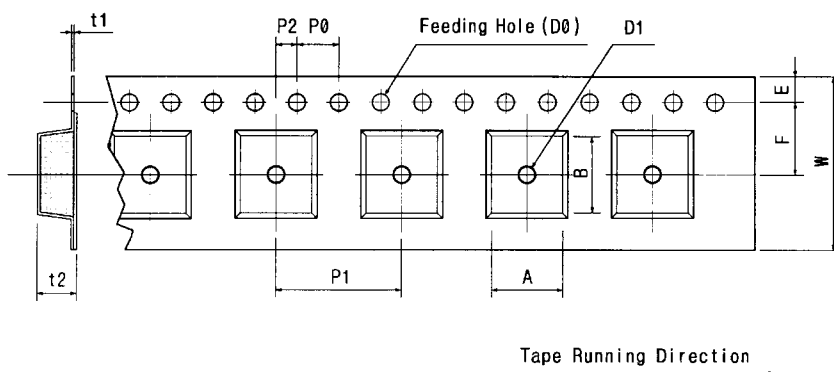
7.1 Tensile Strength of Carrier Tape: 4.4N/mm width

7.2 Top Cover Tape Adhesion (See the below figure)

- (1) pull off angle: 0~15°
- (2) speed: 300mm/min.
- (3) force: 20~70g



[Figure 1] Carrier Tape Dimensions

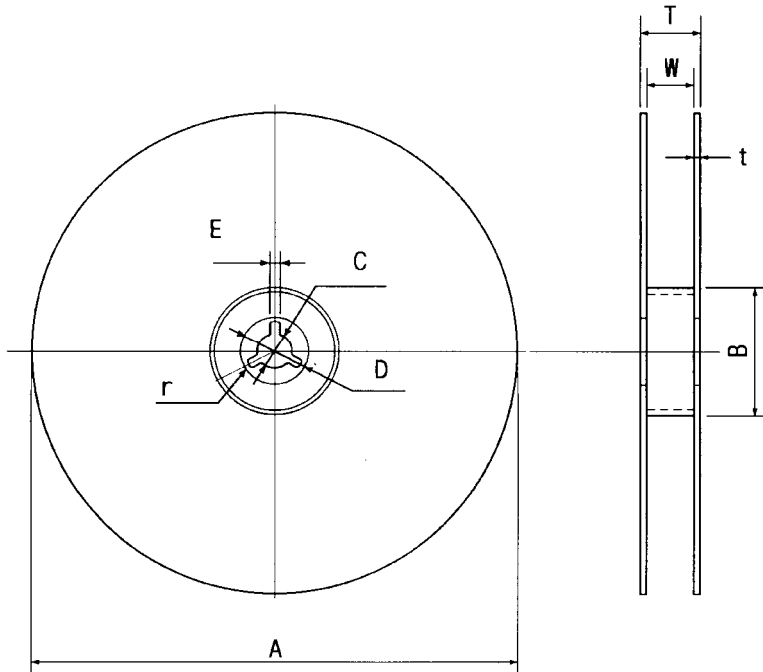


[Unit:mm]

| W     | F     | E     | P0    | P1    | P2    | D0    | D1    | t1    | t2    | A     | B     |
|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|
| 12.00 | 5.50  | 1.75  | 4.00  | 8.00  | 2.00  | Ø1.50 | Ø1.0  | 0.25  | 1.65  | 4.04  | 4.10  |
| ±0.30 | ±0.10 | ±0.10 | ±0.10 | ±0.10 | ±0.10 |       | ±0.25 | ±0.05 | ±0.10 | ±0.10 | ±0.10 |

[Figure 2]

[Unit:mm]



| A    | B    | C    | D    | E    | W    | t    | r    |
|------|------|------|------|------|------|------|------|
| Ø330 | Ø100 | Ø13  | Ø21  | 2    | 13   | 3    | 1.0  |
| ±1.0 | ±0.5 | ±0.5 | ±0.8 | ±0.5 | ±0.3 | max. | max. |